

1. **In the Claims.** The following listing of claims will replace all prior versions of the claims in the application:

1. (Currently Amended) A solder for use in wave-soldering ~~comprising~~consisting of:

from 88.5% to 93.2% tin;

from 3.5% to 4.5% silver;

from 2.0% to 6% indium;

from 0.3% to 1% copper; and

0.01 % phosphorous present in an amount of not more than 0.01%.

2. (Canceled)

3. (Canceled)

4. (Currently Amended) A solder according to claim 1 ~~which comprises further~~consisting of 91.3% tin, 4.2% silver, 4.0% indium, 0.5% copper and 0.01% phosphorous, and said solder having a Young's Modulus of ~~no more than about~~ 9512 MPa.

5. (Canceled)

6. (Currently Amended) A method of preparing a solder for use in wave-soldering process, ~~comprising said method~~consisting of the steps of:

(a) mixing tin, silver, indium, copper and phosphorous to form the solder such that the proportion of tin in the solder is from 88.5% to 93.2%; the proportion of silver in the solder is from 3.5% to 4.5%; the proportion of indium in the solder is from 2.0% to 6%; the proportion of copper in the solder is from 0.3% to 1.0%, and the proportion of phosphorous in the solder is ~~not more than 0.01%, wherein the solder has a Young's Modulus of no more than about 9512 MPa.~~

7. (Canceled)

8. (Canceled)

9. (Currently Amended) A method according to claim 6 ~~which comprises further~~consists of mixing tin, silver, indium, copper and phosphorous such that:

the proportion of tin in the solder is 91.3%;

the proportion of silver in the solder is 4.2%;

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the proportion of indium in the solder is 4%;
the proportion of copper in the solder is 0.5%; and
the proportion of phosphorous is 0.01%.

10. (Canceled)

11. (Currently Amended) A method of soldering, ~~comprising~~ consisting of the steps of:

(a) forming a solder by combining tin, silver, indium, copper and phosphorous in the following proportions:

from 88.5% to 93.2% tin;

from 3.5% to 4.5% silver;

from 2.0% to 6.0% indium;

from 0.3% to 1.0% copper; and

0.01% phosphorous in an amount not more than 0.01%; wherein the solder has a Young's Modulus of ~~no more than about~~ 9512 MPa; and

(b) using the solder formed in step (a) to solder in a wave-soldering process.

12 - 16 (Canceled)